hands-on process of building CCIoT projects via embedded systems, thus enabling them to link theory and practice. There were 30 participants, including students of FSKTM and CE Society members, enrolled for the workshop.

All sessions were conducted by Thinagaran Perumal from the Department of Computer Science and T. Ramachandran and Muhamad Syafiq Mohd Pozi from SEGi University. In the morning session, the participants were introduced to technologies related to CCIoT and various frameworks were discussed so that participants could familiarize themselves with the range of technologies

to be deployed. In addition, the participants were also introduced to Arduino, Raspberry Pi, and bespoke embedded boards as well as IoT data analytics using various frameworks. By the end of the session, the participants demonstrated their mini projects with brief presentations on their project usability. The mentors did a good job by being supportive and encouraging the participants to think outside the box.

The workshop served as an excellent event for participants to listen to the experts and improve their embedded system development skills. With efforts from the CE Society Malaysia Chapter, Universiti Putra Malaysia, and the participants, the workshop proved to be a great success and an ideal platform to nurture interest in embedded system project development for CE. The Malaysia Chapter plans to organize a series of similar CCIoT sessions in the near future. A very engaged discussion progressed among the participants, especially on IoT visions for CE, which concluded the workshop as the closing agenda.

> —Thinagaran Perumal **IEEE CE Society** Malaysia Chapter

IEEE Consumer Electronics Society Sponsors the Smart Village Program

n March 2015, the IEEE Consumer Electronics Society Board of Governors voted to become a sponsor of the IEEE Smart Village Program. This program was organized by the IEEE Foundation and is cosponsored by other IEEE organizational units. In April 2015, the IEEE Smart Village initiative received prestigious high-level recognition from the Bloomberg New Energy Finance (BNEF), Finance for Resilience (FiRe) initiative.

The IEEE Smart Village's proposal was selected as one of eight finalists for the BNEF FiRe initiative with its submission, "Scalable DC Microgrids-Scalability and Sustainability Through Standards." The proposal highlighted IEEE Smart Village's charge to create connectable, scalable, dc microgrids that leverage new standards to advance the spread of electrical goods and communications access for developing countries.



Students in Muhuru Bay, Kenya, have had their lives changed by IEEE Smart Village.

FiRe is designed to identify the best proposals to spur increased investment for clean energy, climate, sustainability, and green growth. As a finalist, IEEE Smart Village was invited to the BNEF Future of Energy Summit—Opportunities in Transformation in New York to pitch the proposal. The summit gathered over 1,200 major decision-makers intent on shaping the future of energy. Attendees from diverse sectors, including investment banking and finance, corporations, governmental entities, and nonprofits, learned about the IEEE Smart Village mission and vision.

Being named a FiRe finalist represents an incredible opportunity for the IEEE Smart Village program to achieve awareness and recognition among influential global energy leaders. By participating in this summit, a number of potential financial champions for IEEE Smart Village were identified, and in the coming weeks and months, the IEEE Smart Village team will work hard to pursue those funding partnerships.

Partnerships between the IEEE Foundation and Societies like the Consumer Electronics (CE) Society to support humanitarian initiatives like this are a great way to make a difference and support the IEEE motto of "Advancing Technology for Humanity." These activities also connect our Society with

corporate humanitarian efforts going on at many companies in the CE industry. We look forward to further efforts to increase the participation of the CE Society on efforts that help the consumers of electronics.

—Tom Coughlin

Membership Drive by CESoc Malaysia

he IEEE Consumer Electronics Society Malaysia Chapter (CESoc Malaysia) began its annual session strategy for the year 2015 with its most important assignment—the membership drive. Since members are crucial for Chapters to implement activities, new membership enrollment from undergraduate students and retaining previous memberships has always been a priority.

The membership drive and professional session took place at MAHSA University, Kuala Lumpur, on 28 March 2015. The membership drive was aimed at educating undergraduate students about the IEEE and the IEEE Consumer Electronics (CE) Society, the benefits of being Society volunteers, accessing the Society's publications, and various CE conferences and opportunities for students.

Several interactive sessions were conducted in parallel, and students had the opportunity to choose which session to attend. The interactive session began with an opening speech by the Dr. Thinagaran Perumal, Chapter chair of CESoc Malaysia, who provided an overview of the CE Society, values and responsibilities for being IEEE volunteers, as well as the membership benefits of both IEEE and the CE Society. The interactive sessions were divided into five slots with groups of students from various engineering



Student Members signing up for IEEE and CESoc memberships.



CESoc ExCom and Student Members.

backgrounds. Each session was allotted an Executive Committee (ExCom) member.

The interactive session within the group began with each ExCom member introducing themselves; two-way feedback queries were made by the ExCom members regarding their opinion on the

IEEE, volunteering expectations, and their interest in CE-related aspects. Next, the ExCom members detailed the origin of IEEE and its benefits, the registration fee, and the function of the CESoc Malaysia Chapter. *IEEE Spectrum* and brochures were passed among

Digital Object Identifier 10.1109/MCE.2015.2431392
Date of publication: 15 July 2015